ELSEVIER

Colloids and Surfaces
A: Physicochemical and Engineering Aspects 165 (2000) 425

COLLOIDS AND SURFACES A

www.elsevier.nl/locate/colsurfa

Author Index

Adamczyk, Z., 157
Ahmadi, G., 189
Ala-Nissila, T., 209
Alava, M., 209
Asikainen, J., 209

Bai, R., 95
Bartelt, M.C., 373
Bhattacharjee, S., 143
Bišćan, J., 115
Borkovec, M., 79
Busnaina, A.A., 3

Chen, J.Y., 143

Eklund, E., 11
Elimelech, M., 143
Evans, J.W., 241, 373

Haataja, M., 209
Hannon, J.B., 373
Hart, S.C., 189
Hays, D., 11

James, E.W., 241
Jullien, R., 405

Kallay, N., 115
Koper, G.J.M., 39

Lenhoff, A.M., 125
Liu, D.-J., 241

Majaniemi, S., 209
Matijević, E., 59
Meakin, P., 405
Mizes, H., 11

Oberholzer, M.R., 125
Ott, M., 11

Percus, J.K., 345
Privman, V., 231
Provatas, N., 209

Quesnel, D.J., 3

Ramsden, J.J., 25
Rička, J., 79
Rimai, D.S., 3
Ryde, N.P., 59

Schaaf, P., 255
Schmid, A.K., 373
Semmler, M., 79
Senger, B., 255
Smolić, T., 115
Soltani, M., 189
Stoldt, C.R., 373
Szyk-Warszyńska, L., 157

Talbot, J., 287
Tarjus, G., 287
Tien, C., 95

Van Tassel, P.R., 287
Viot, P., 287
Voegel, J.-C., 255

Wang, J.-S., 325
Warszyński, P., 157
Weroński, P., 157
Woo Lee, J., 363

Yuan, Y., 125

PII: S0927-7757(99)00533-6

ELSEVIER

Colloids and Surfaces
A: Physicochemical and Engineering Aspects 165 (2000) 427–428

COLLOIDS AND SURFACES A

www.elsevier.nl/locate/colsurfa

Subject Index

Adhesion, 11, 115
Adhesion of particles, 59
Adhesion rate constant, 115
Amidine latex, 79
Arrays, 25
Association, 25
Atomic force, 11
Atomic force microscopy, 79

Bethe lattice, 345
Binary mixtures, 363

Car parking, 287
Centrifugal, 11
Charged colloidal particles, 125
Chemisorption, 241
Cobalt, 373
Colloidal films, 39
Colloidal particles, 255
Colloid particle deposition, 157
Colloids, 231
Colloid stability, 115
Computer simulations, 405
Continuum percolation, 209
Convective effects in particle deposition, 157
Copper, 373

Deposition, 325
Deposition equations, 95
Deposition models, 209
Deposition of particles, 59
Deposition of particles of collectors, 157
Derjaguin's approximation, 0
Desorption, 241
Detachment, 11
Detachment of particles, 59
Diffusion, 241
Diffusional deposition, 79
Dimensionality, 25
Dissociation, 25
DLVO interaction, 0
Dry particles, 3

Electrostatic effects, 189
Electrostatic interactions, 79
Epitaxy, 373
Etching, 373

Fiber networks, 209
Fiber resuspension, 189

Gaussian model, 345
Granular media, 95
Growth, 373

Hydrodynamic effects in colloid deposition, 157

Interaction energy, 115
Ionic strength, 125
Irreversible deposition processes, 255
Irreversible random sequential adsorption, 363
Iso-electric point, 115

Lattice site, 325
Line segments, 363
Low-energy electron microscopy, 373
Low-index single crystal surfaces., 373

Mean spherical model, 345
Microscopy, 11
Models of non-equilibrium phenomena, 373

Nanometer to micrometer size, 3
Next neighbor exclusion, 345
Nonequilibrium dynamical models, 231
Non-uniform flux, 345
Nucleation, 373
Numerical solution, 95

Optical properties, 39
Oxygen, 373

PII: S0927-7757(99)00534-8

Packed column technique, 59
Paper structure, 209
Particle, 11
Particle adhesion, 3
Particle deposition, 0, 95
Particle relaxation, 325
Point of zero charge, 115
Polydispersity, 79
Protein, 25
Protein adsorption, 287

Quantum field representation, 345

Random deposition, 405
Random sequential adsorption, 79, 125, 231, 241, 325, 345
Relaxation, 241
Removal of adhered particles, 59
Ruthenium, 373

Scanning angle reflectometry, 39
Scanning tunneling microscopy, 373
Sequential adsorption processes, 287
Silicon, 373
Silicone nitride, 115
Solid substrates, 255
Spatial correlations, 209
Spheroidal particle, 0
Steepest descent ballistic deposition, 405
Surface element integration, 0
Surface interactions, 95

Transient behavior, 95
Turbulent boundary layer, 189

Xerography, 11